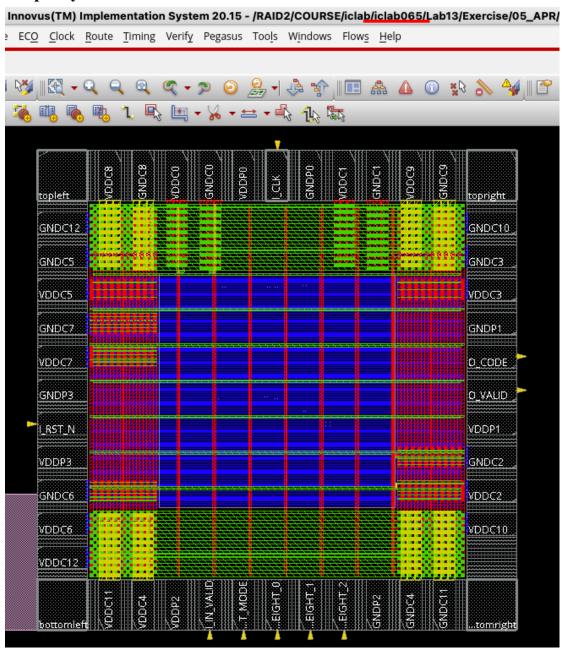
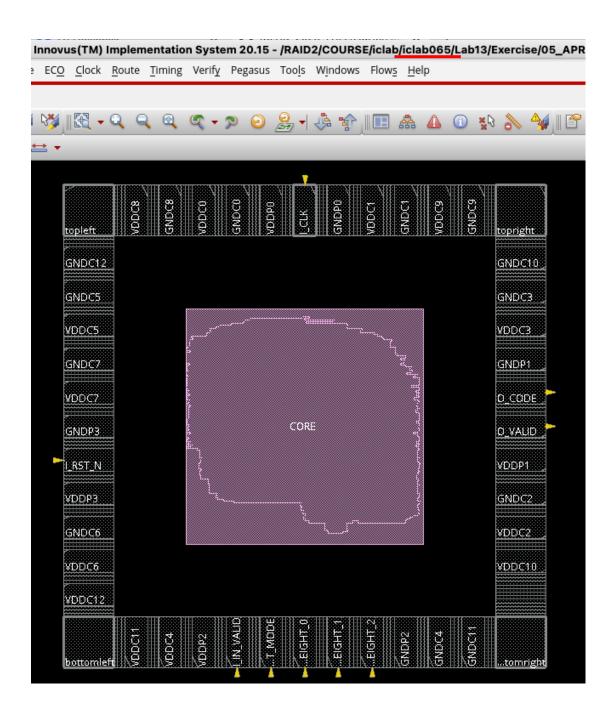
Report

1. Chip Layout View:



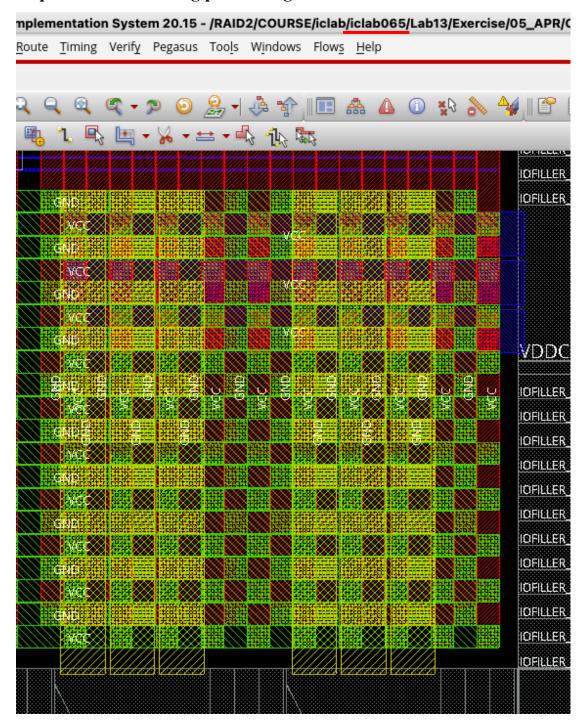


2. Core to IO boundary:

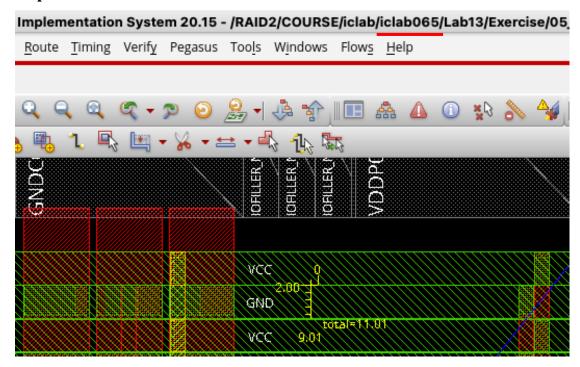
tion System 20.15 - /RAID2/COURSE/iclab/iclab065/Lab13/Exercise/05_APF X Specify Floorplan — ee24 Basic Advanced **Design Dimensions** Specify By:
Size
Die/IO/Core Coordinates Ratio (H/W): 276238074 Core Size by: Sapect Ratio: Core Utilization: 1.0 Cell Utilization: 1.0 Dimension: Width: 660.3 Height: 655.2 Width: Die Size by: 1341.06 1341.06 Height: Core Margins by:
Ore to IO Boundary Core to Die Boundary Core to Left: 200.26 Core to Top: 204.14 Core to Right: 200.26 Core to Bottom: 201.48 Die Size Calculation Use: O Max IO Height Min IO Height Floorplan Origin at: Lower Left Corner
 Center Unit: Micron

3. Core Ring:

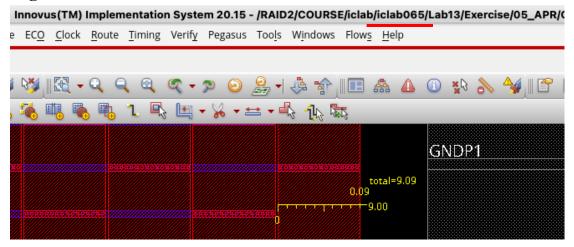
10 pairs & interleaving power ring



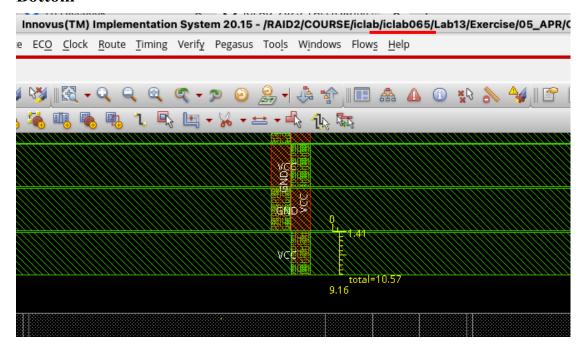
Top



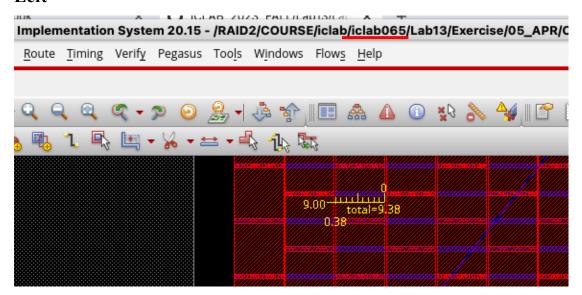
Right



Bottom



Left

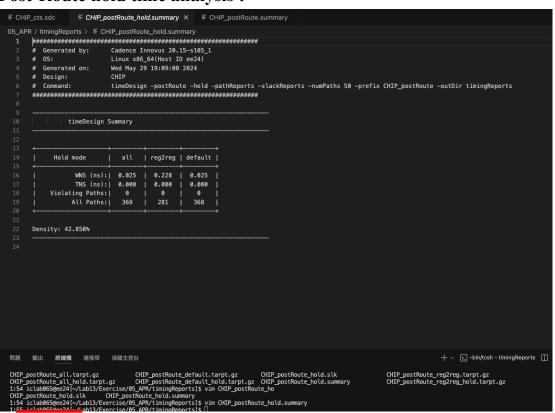


(Width settings are all 9)

4. Post-Route setup time analysis:



5. Post-Route hold time analysis:



6. DRC result:

```
wangyu — ssh -p 415 -X iclab065@140.113.201.24 — 415 — ssh -p 415 -X iclab065@140.113.201.24 — 107...

VERIFY DRC ..... Sub-Area : 24 complete 0 Viols.

VERIFY DRC ..... Sub-Area: {1075.200 1075.200 1341.060 1341.060} 25 of 25

VERIFY DRC ..... Sub-Area : 25 complete 0 Viols.

Verification Complete : 0 Viols.

*** End Verify DRC (CPU: 0:00:01.5 ELAPSED TIME: 1.00 MEM: 51.0M) ***
```

7. LVS result:

8. Post Layout simulation result :

```
PASS PATTERN NO.1992
PASS PATTERN NO.1993
PASS PATTERN NO.1994
PASS PATTERN NO.1995
PASS PATTERN NO.1996
PASS PATTERN NO.1996
PASS PATTERN NO.1998
PASS PATTERN NO.1999

Congratulations!
You have passed all patterns!
Your execution cycles = 32000 cycles
Your clock period = 20.0 ns
Total Latency = 640000.0 ns

$finish called from file "PATTERN.v", line 36.
$finish at simulation time 1819630000
V C S S i m u la ti on R e p o r t

Time: 1819630000 ps
CPU Time: 28.590 seconds; Data structure size: 2.2Mb
Thu May 30 02:09:38 2024
CPU time: 1.820 seconds to compile + .421 seconds to elab + .658 seconds to link + 28.671 seconds in simulation 2:09 iclab065@ee24[~/Lab13/Exercise/06_POST]$

■
```

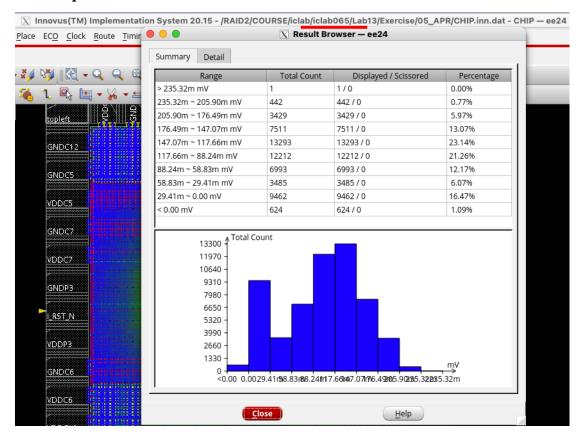
9. Power result:

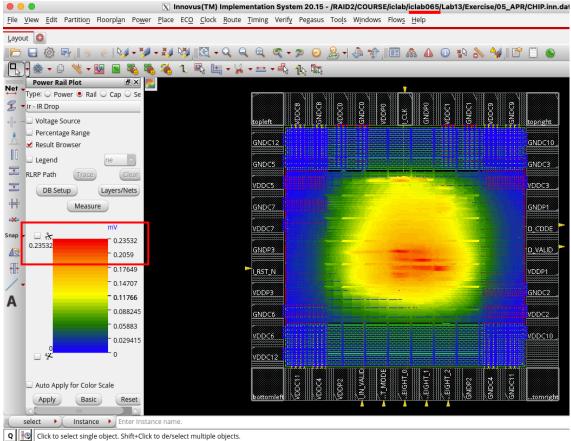
```
● ● ■ wangyu — ssh -p 415 -X iclab065@140.113.201.24 — 415 — ssh -p 415 -X iclab065@140.113.201.24 — 107...

Total Power

Total Internal Power: 1.40460332 58.4674%
Total Switching Power: 1.36979407 49.2167%
Total Leakage Power: 0.00879143 0.3159%
Total Power: 2.78318882
```

10. IR Drop Results:





Method:

IR drop refers to the voltage reduction that happens as current travels through a conductor. It follows Ohm's Law (V = IR), where V is voltage, I is current, and R is resistance. In simpler terms, some voltage is "lost" due to the resistance of the wires.

To cope with this problem, I placed 13 sets of core power pads and set up tighter stripes.

These methods worked very well and the final IR drop was less than 0.25mV.